

TDA7563PD

Multifunction quad power amplifier with built-in diagnostics features

Features

- Multipower BCD technology
- MOSFET output power stage
- DMOS power output
- Non switching high efficiency
- High output power capability 4x28W/4Ω @ 14.4V, 1kHz, 10% THD, 4x40W EIAJ
- Max. output power 4x72W/2Ω
- Full I²C bus driving:
 - Standby
 - Independent front/rear soft play/mute
 - Selectable gain 30dB /16dB (for low noise line output function)
 - High efficiency enable/disable
 - I²C bus digital diagnostics
- Full fault protection
- DC offset detection
- Four independent short circuit protection
- Clipping detector pin with selectable threshold (2%/10%)
- Standby/mute pin
- Linear thermal shutdown
- ESD protection



Description

The TDA7563PD is a new BCD technology Quad Bridge type of car radio amplifier in PowerSO36 package specially intended for car radio applications.

Thanks to the DMOS output stage the TDA7563PD has a very we distortion allowing a clear powerful sound. Among the features, its superior efficiency referenance coming from the internal exclusive structure, makes it the most suitable device to simplify the thermal management in high power sets.

The dissipated output power under average listening condition is in fact reduced up to 50% when compared to the level provided by conventional class AB solutions.

This device is equipped with a full diagnostics array that communicates the status of each speaker through the I²C bus.

Table 1. Device summary

Order code	Package	Packing
TDA7563PDTR	PowerSO36 (slug up)	Tape and reel
TDA7563PD	PowerSO36 (slug up)	Tube

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1 Block, pins connection and application diagrams

Figure 1. Block diagram

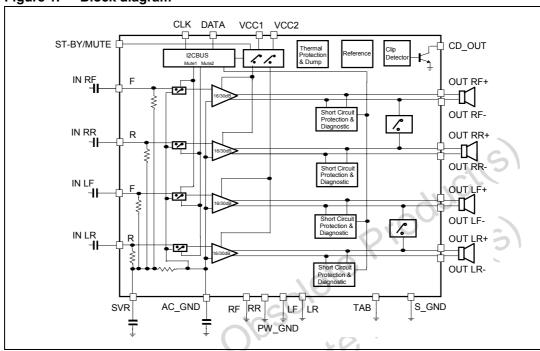
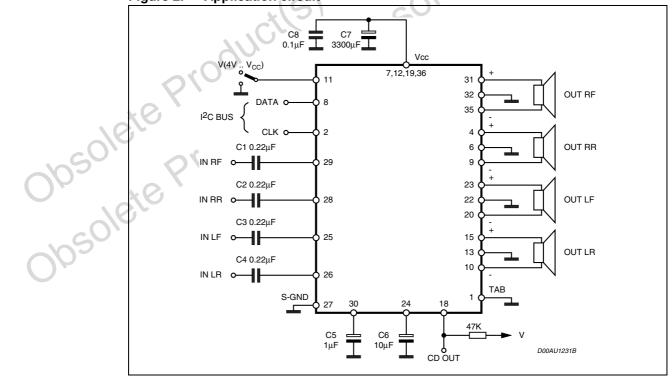


Figure 2. Application circuit



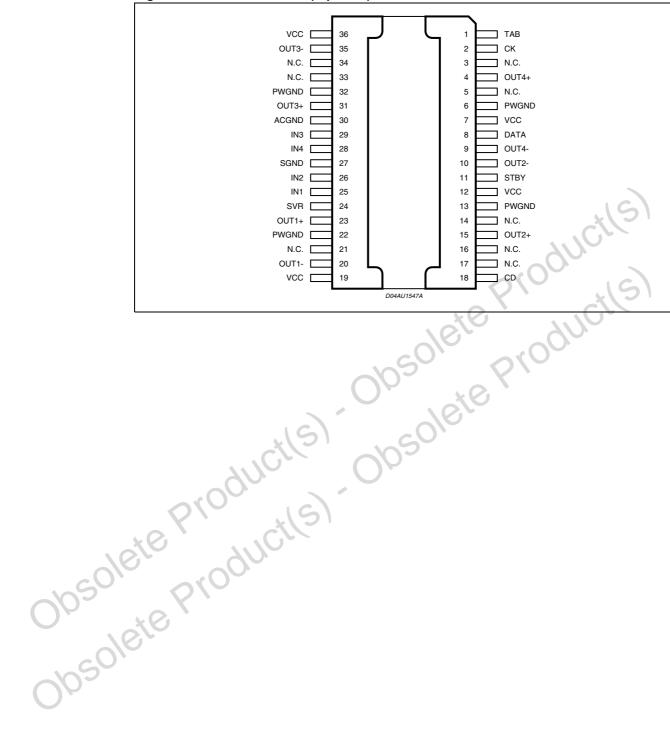


Figure 3. Pin connection (top view)

Electrical specifications 2

2.1 **Absolute maximum ratings**

Table 1. **Absolute maximum ratings**

Symbol	Parameter	Value	Unit			
V _{op}	Operating supply voltage	18	V			
V _S	DC supply voltage	28	V			
V _{peak}	Peak supply voltage (for t = 50ms)	50	V			
V _{CK}	CK pin voltage	6	V			
V _{DATA}	Data pin voltage	6	V			
Io	Output peak current (not repetitive t = 100ms)	8	Α			
Io	Output peak current (repetitive f > 10Hz)	6	Α			
P _{tot}	Power dissipation T _{case} = 70°C	85	8			
T _{stg} , T _j	Storage and junction temperature	-55 to 150	°C			
Therm	Thermal data					
Symbol	Parameter	Value	Unit			

Thermal data 2.2

Table 2. Thermal data

Symbol	Parameter	~O/O	Value	Unit
R _{th j-case}	Thermal resistance junction to case	Max	1	°C/W

Electrical characteristics 2.3

Table 3. **Electrical characteristics**

(Refer to the test circuit, $V_S = 14.4V$; f=1kHz; $R_L=4\Omega$; $T_{amb}=25$ °C unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
Power an	nplifier					
Vs	Supply voltage range		8		18	V
I _d	Total quiescent drain current			170	300	mA
03		EIAJ (V _S = 13.7V)	35	40		W
		THD = 10% THD = 1%	25	28 22		W W
P _O	Output power	$R_L = 2\Omega$; EIAJ ($V_S = 13.7V$) $R_L = 2\Omega$; THD 10% $R_L = 2\Omega$; THD 1% $R_L = 2\Omega$; max power	55 40	62 46 35 72		W W W

Table 3. Electrical characteristics (continued)

(Refer to the test circuit, $V_S = 14.4V$; f=1kHz; R_L =4 Ω ; T_{amb} = 25°C unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
		P _O = 1 to 10W; STD mode		0.03	0.1	%
		HE MODE; $P_O = 1.5W$		0.03	0.1	%
THD	Total harmonic distortion	HE MODE; P _O = 8W		0.15	0.5	%
1110	Total namionio diotoritori	$P_{O} = 1 \text{ to } 10W, f = 10kHz$		0.2	0.5	%
		G _V = 16dB; STD mode		0.02	0.05	%
		$V_O = 0.1 \text{ to } 5 \text{ V}_{RMS}$				
C _T	Cross talk	$f = 1 \text{kHz to } 10 \text{kHz}, R_g = 600\Omega$	50	60		dB
R _{IN}	Input impedance		60	100	130	ΚΩ
G _{V1}	Voltage gain 1		29.5	30	30.5	dB
ΔG_{V1}	Voltage gain match 1		-1	AV	1	dB
G _{V2}	Voltage gain 2		15.5	16	16.5	dB
ΔG_{V2}	Voltage gain match 2		-1		1	dB
E _{IN1}	Output noise voltage 1	Rg = 600Ω ; filter 20 Hz to 22 kHz		50	100	μV
E _{IN2}	Output noise voltage 2	Rg = 600Ω ; G _V = $16dB$		15	30	μV
□IN2	Output hoise voitage 2	filter 20 Hz to 22 kHz	01		30	μν
SVR	Supply voltage rejection	$f = 100Hz$ to $10kHz$; $V_r = 1Vpk$; $R_g = 600\Omega$	50	60		dB
BW	Power bandwidth	10	100			kHz
A _{SB}	Standby attenuation	51 60,	90	110		dB
I _{SB}	Standby current	003		2	10	μΑ
A _M	Mute attenuation		80	100		dB
V _{OS}	Offset voltage	Mute & play	-100	0	100	mV
V _{AM}	Min. supply mute threshold	(3)	7	7.5	8	V
T _{ON}	Turn on delay	D2/D1 (IB1) 0 to 1		5	20	ms
T _{OFF}	Turn off delay	D2/D1 (IB1) 1 to 0		5	20	ms
V _{SBY}	Standby/mute pin for standby		0		1.5	V
V _{MU}	Standby/mute pin for mute		3.5		5	V
V _{OP}	Standby/mute pin for operating		7		V _S	V
-0	Ctandby/myta nin symmet	V _{standby/mute} = 8.5V		20	40	μА
I _{MU}	Standby/mute pin current	V _{standby/mute} < 1.5V		0	10	μΑ
CD _{LK}	Clip det. high leakage current	CD off		0	15	μΑ
CD _{SAT}	Clip det. saturation voltage	CD on; I _{CD} = 1mA		300		mV
CD	Clin det TUD level	D0 (IB1) = 1	5	10	15	%
CD _{THD}	Clip det. THD level	D0 (IB1) = 0	1	2	3	%

Table 3. Electrical characteristics (continued) (Refer to the test circuit, $V_S = 14.4V$; f=1kHz; $R_L=4\Omega$; $T_{amb}=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
Turn on o	liagnostics 1 (Power amplifier r	node)		I	<u>I</u>	
Pgnd	Short to GND det. (below this limit, the output is considered in short circuit to GND)				1.2	V
Pvs	Short to Vs det. (above this limit, the output is considered in short circuit to VS)		Vs -1.2			V
Pnop	Normal operation thresholds. (within these limits, the output is considered without faults).	Power amplifier in standby	1.8		Vs -1.8	Y
Lsc	Shorted load det.			111	0.5	Ω
Lop	Open load det.		130	70,		Ω
Lnop	Normal load det.		1.5		70	Ω
Turn on o	liagnosticS 2 (Line driver mode	× (2)			CI	
Pgnd	Short to GND det. (below this limit, the output is considered in short circuit to GND)	Power amplifier in standby	01	ogi	1.2	٧
Pvs	Short to Vs det. (above this limit, the output is considered in short circuit to VS)	oleje	Vs -1.2			V
Pnop	Normal operation thresholds. (within these limits, the output is considered without faults).	(3) Obso.	1.8		Vs -1.8	V
Lsc	Shorted load det.	_ /			1.5	Ω
Lop	Open load det.	5	400			Ω
Lnop	Normal load det.		4.5		200	Ω
Permane	nt diagnostics 2 (Power amplifi	er mode or line driver mode)			l.	
Pgnd	Short to GND det. (below this limit, the output is considered in short circuit to GND)				1.2	٧
Pvs	Short to Vs det. (above this limit, the output is considered in short circuit to Vs)	Power amplifier in mute or play, one or more short circuits protection activated	Vs -1.2			٧
Pnop	Normal operation thresholds. (within these limits, the output is considered without faults).		1.8		Vs -1.8	٧
	Shorted load det.	Power amplifier mode			0.5	Ω
L _{SC}	Shorted load det.	Line driver mode			1.5	Ω
V _O	Offset detection	Power amplifier in play AC input signals = 0	±1.5	±2	±2.5	٧

Table 3. Electrical characteristics (continued)

(Refer to the test circuit, $V_S = 14.4V$; f=1kHz; $R_L=4\Omega$; $T_{amb}=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
I _{NL}	Normal load current detection	V _O < (V _S -5)pk	500			mA
I _{OL}	Open load current detection	1 00 < (08-2)bk			250	mA
I ² C bus in	nterface					
S _{CL}	Clock frequency				400	kHz
V _{IL}	Input low voltage				1.5	V
V _{IH}	Input high voltage		2.3			V

2.4 Electrical characteristics curves

Figure 4. Quiescent current vs. supply voltage Figure 5. Output power vs. supply voltage (4Ω)

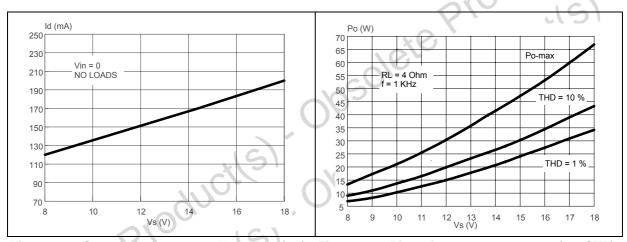


Figure 6. Output power vs. supply voltage (2 Ω) Figure 7. Distortion vs. output power (4 Ω , STD)

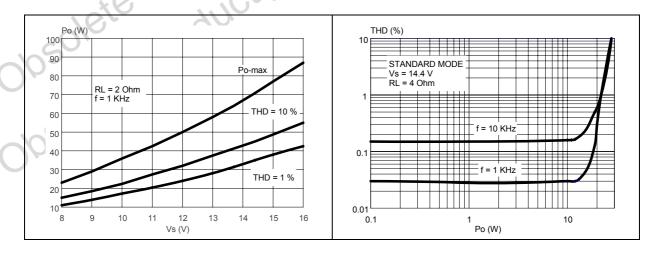


Figure 8. Distortion vs. output power (4 Ω , HI- Figure 9. Distortion vs. output power (2 Ω , STD)

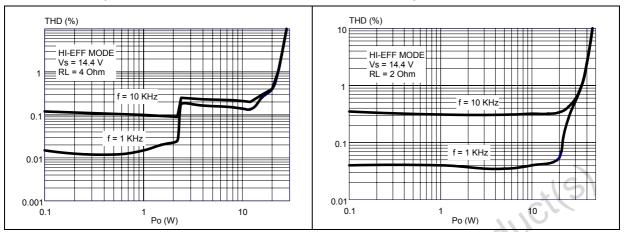


Figure 10. Distortion vs. frequency (4Ω)

Figure 11. Distortion vs. frequency (2 Ω)

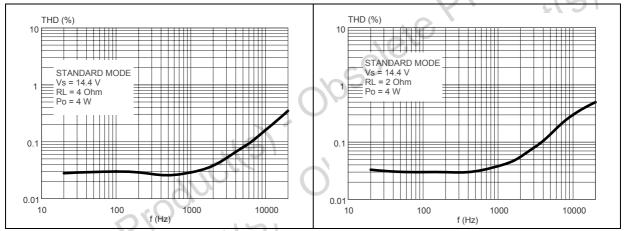


Figure 12. Crosstalk vs. frequency

Figure 13. Supply voltage rejection vs. frequency

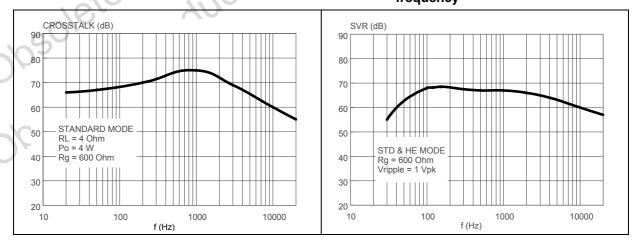
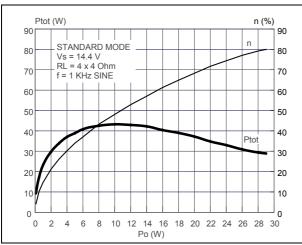


Figure 14. Power dissipation and efficiency vs. Figure 15. Power dissipation and efficiency vs. output power (4Ω , STD, SINE) output power (4Ω , HI-EFF, SINE)



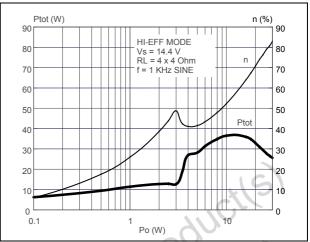
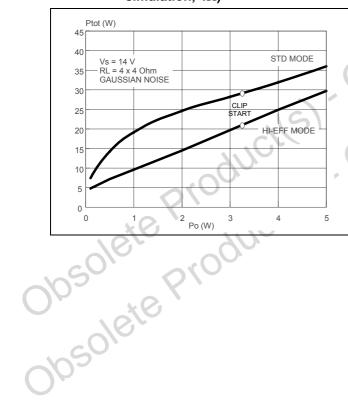
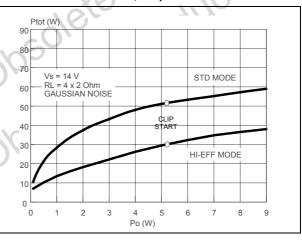


Figure 16. Power dissipation vs. average output power (audio program simulation, 4Ω)

Figure 17. Power dissipation vs. average output power (audio program simulation, 2Ω)





Diagnostics functional description 3

3.1 **Turn-on diagnostic**

It is activated at the turn-on (standby out) under I²C bus request. Detectable output faults are:

- SHORT TO GND
- SHORT TO Vs
- SHORT ACROSS THE SPEAKER
- **OPEN SPEAKER**

To verify if any of the above misconnections are in place, a subsonic (inaudible) current pulse (Figure 18) is internally generated, sent through the speaker(s) and sunk back. The Turn On diagnostic status is internally stored until a successive diagnostic pulse is requested (after a I²C reading).

If the "standby out" and "diagnostic enable" commands are both given through a single programming step, the pulse takes place first (power stage still in standby mode, low, outputs = high impedance).

Afterwards, when the amplifier is biased, the PERMANENT diagnostic takes place. The previous Turn On state is kept until a short appears at the outputs.

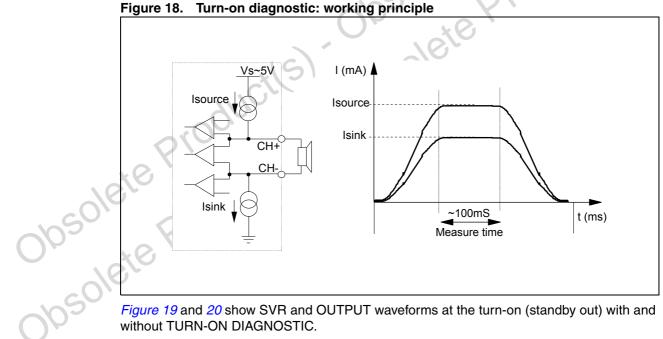


Figure 19 and 20 show SVR and OUTPUT waveforms at the turn-on (standby out) with and without TURN-ON DIAGNOSTIC.

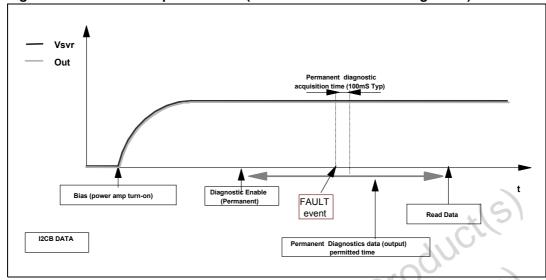
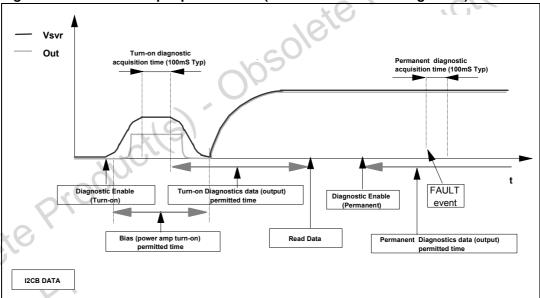


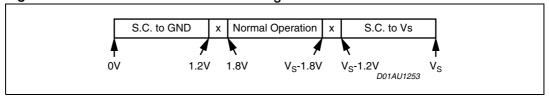
Figure 19. SVR and output behavior (case 1: without turn-on diagnostic)

Figure 20. SVR and output pin behavior (case 2: with turn-on diagnostic)



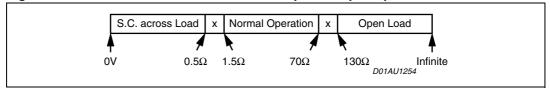
The information related to the outputs status is read and memorized at the end of the current pulse top. The acquisition time is 100 ms (typ.). No audible noise is generated in the process. As for SHORT TO GND / $V_{\rm S}$ the fault-detection thresholds remain unchanged from 30 dB to 16 dB gain setting. They are as follows:TDA7563PD

Figure 21. Thresholds for short to GND/V_S



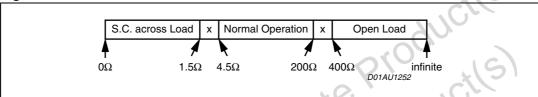
Concerning SHORT ACROSS THE SPEAKER / OPEN SPEAKER, the threshold varies from 30 dB to 16 dB gain setting, since different loads are expected (either normal speaker's impedance or high impedance). The values in case of 30 dB gain are as follows:

Figure 22. Thresholds for short across the speaker/open speaker



If the Line-Driver mode (Gv= 16 dB and Line Driver Mode diagnostic = 1) is selected, the same thresholds will change as follows:

Figure 23. Thresholds for line-drivers



3.2 Permanent diagnostics

Detectable conventional faults are:

- Short to GND
- Short to Vs
- Short across the speaker

The following additional features are provided:

Output offset detection

The TDA7563PD has 2 operating statuses:

- 1. RESTART mode. The diagnostic is not enabled. Each audio channel operates independently from each other. If any of the a.m. faults occurs, only the channel(s) interested is shut down. A check of the output status is made every 1 ms (*Figure 24*). Restart takes place when the overload is removed.
- 2. DIAGNOSTIC mode. It is enabled via I²C bus and self activates if an output overload (such to cause the intervention of the short-circuit protection) occurs to the speakers outputs. Once activated, the diagnostics procedure develops as follows (*Figure 25*):
 - To avoid momentary re-circulation spikes from giving erroneous diagnostics, a check of the output status is made after 1ms: if normal situation (no overloads) is detected, the diagnostic is not performed and the channel returns back active.
 - Instead, if an overload is detected during the check after 1 ms, then a diagnostic cycle having a duration of about 100 ms is started.
 - After a diagnostic cycle, the audio channel interested by the fault is switched to RESTART mode. The relevant data are stored inside the device and can be read by the microprocessor. When one cycle has terminated, the next one is activated

- by an I²C reading. This is to ensure continuous diagnostics throughout the carradio operating time.
- To check the status of the device a sampling system is needed. The timing is chosen at microprocessor level (over half a second is recommended).

Figure 24. Restart timing without diagnostic enable (permanent) - Each 1ms time, a sampling of the fault is done

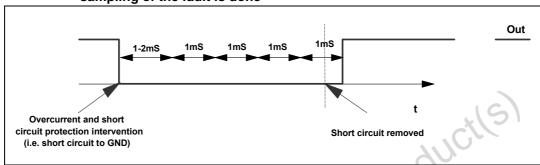
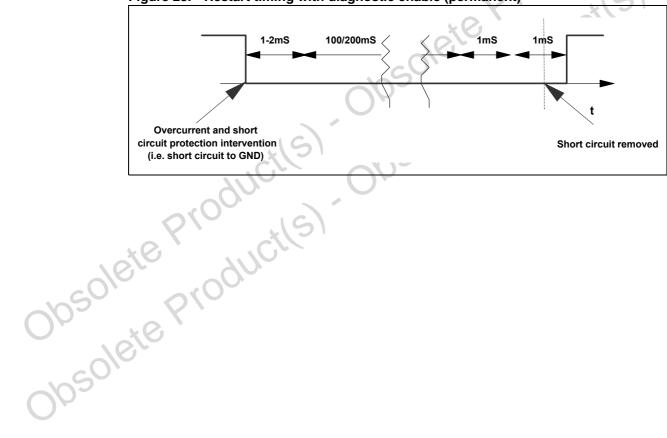


Figure 25. Restart timing with diagnostic enable (permanent)



Output DC offset detection 4

Any DC output offset exceeding ±2 V are signalled out. This inconvenient might occur as a consequence of initially defective or aged and worn-out input capacitors feeding a DC component to the inputs, so putting the speakers at risk of overheating.

This diagnostic has to be performed with low-level output AC signal (or Vin = 0).

The test is run with selectable time duration by microprocessor (from a "start" to a "stop" command):

- START = Last reading operation or setting IB1 D5 (OFFSET enable) to 1
- STOP = Actual reading operation

Excess offset is signalled out if persistent throughout the assigned testing time. This feature is disabled if any overloads leading to activation of the short-circuit protection occurs in the process.

4.1 Multiple faults

When more misconnections are simultaneously in place at the audio outputs, it is quaranteed that at least one of them is initially read out. The others are notified after successive cycles of I²C reading and faults removal, provided that the diagnostic is enabled. This is true for both kinds of diagnostic (Turn on and Permanent).

The table below shows all the couples of double-fault possible. It should be taken into account that a short circuit with the 4 ohm speaker unconnected is considered as double fault.

Table 4.	Double fault table for turn on diagnostic	

	S. GND (so)	S. GND (sk)	S. Vs	S. Across L.	Open L.
S. GND (so) S. GND	S. GND	S. Vs + S. GND	S. GND	S. GND
S. GND (sk	(i)	S. GND	S. Vs	S. GND	Open L. (*)
S. Vs	900	/	S. Vs	S. Vs	S. Vs
S. Across I	/	/	/	S. Across L.	N.A.
Open L.	/	/	/	/	Open L. (*)

S. GND (so) / S. GND (sk) in the above table make a distinction according to which of the 2 outputs is shorted to ground (test-current source side= so, test-current sink side = sk). More precisely, in Channels LF and RR, so = CH+, sk = CH-; in Channels LR and RF, so = CH-, sk = CH+.

In Permanent Diagnostic the table is the same, with only a difference concerning Open Load(*), which is not among the recognizable faults. Should an Open Load be present during the device's normal working, it would be detected at a subsequent Turn on Diagnostic cycle (i.e. at the successive Car Radio Turn on).

4.2 Faults availability

All the results coming from I^2C bus, by read operations, are the consequence of measurements inside a defined period of time. If the fault is stable throughout the whole period, it will be sent out.

To guarantee always resident functions, every kind of diagnostic cycles (Turn on, Permanent, Offset) will be reactivate after any I²C reading operation. So, when the micro reads the I²C, a new cycle will be able to start, but the read data will come from the previous diag. cycle (i.e. The device is in Turn On state, with a short to GND, then the short is removed and micro reads I²C. The short to GND is still present in bytes, because it is the Obsolete Product(s)

Obsolete Product(s)

Obsolete Product(s)

Obsolete Product(s) result of the previous cycle. If another I²C reading operation occurs, the bytes do not show the short). In general to observe a change in Diagnostic bytes, two I²C reading operations

TDA7563PD Thermal protection

5 Thermal protection

Thermal protection is implemented through thermal foldback (Figure 26).

Thermal foldback begins limiting the audio input to the amplifier stage as the junction temperatures rise above the normal operating range. This effectively limits the output power capability of the device thus reducing the temperature to acceptable levels without totally interrupting the operation of the device.

The output power will decrease to the point at which thermal equilibrium is reached. Thermal equilibrium will be reached when the reduction in output power reduces the dissipated power such that the die temperature falls below the thermal foldback threshold. Should the device cool, the audio level will increase until a new thermal equilibrium is reached or the amplifier reaches full power. Thermal foldback will reduce the audio output level in a linear manner.

Three Thermal warning are available through the I²C bus data.

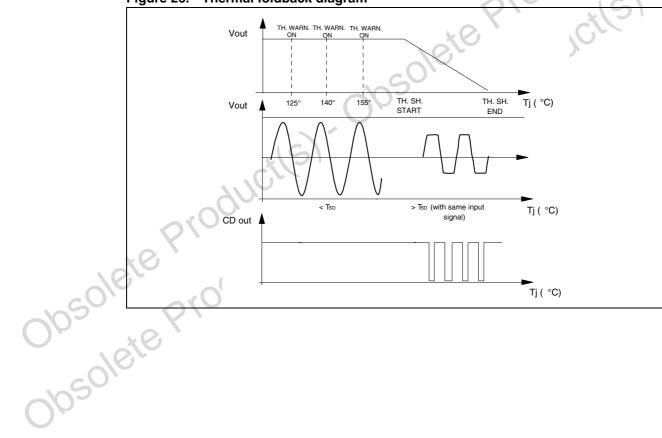


Figure 26. Thermal foldback diagram

I2C bus TDA7563PD

6 I²C bus

6.1 I²C programming/reading sequences

A correct turn on/off sequence respectful of the diagnostic timings and producing no audible noises could be as follows (after battery connection):

TURN-ON: PIN2 > 7V --- 10ms --- (STANDBY OUT + DIAG ENABLE) --- 500 ms (min) --- MUTING OUT

TURN-OFF: MUTING IN --- 20 ms --- (DIAG DISABLE + STANDBY IN) --- 10ms --- PIN2 = 0

Car Radio Installation: PIN2 > 7V --- 10ms DIAG ENABLE (write) --- 200 ms --- I²C read (repeat until All faults disappear).

OFFSET TEST: Device in Play (no signal) -- OFFSET ENABLE - 30ms - I^2 C reading (repeat I^2 C reading until high-offset message disappears).

6.2 I²C bus interface

Data transmission from microprocessor to the TDA7563PD and vice versa takes place through the 2 wires I²C bus interface, consisting of the two lines SDA and SCL (pull-up resistors to positive supply voltage must be connected).

6.3 Data validity

As shown by *Figure 27*, the data on the SDA line must be stable during the high period of the clock.

The HIGH and LOW state of the data line can only change when the clock signal on the SCL line is LOW.

6.4 Start and stop conditions

As shown by *Figure 28* a start condition is a HIGH to LOW transition of the SDA line while SCL is HIGH.

The stop condition is a LOW to HIGH transition of the SDA line while SCL is HIGH.

6.5 Byte format

Every byte transferred to the SDA line must contain 8 bits. Each byte must be followed by an acknowledge bit. The MSB is transferred first.

TDA7563PD I2C bus

6.6 Acknowledge

The transmitter^(*) puts a resistive HIGH level on the SDA line during the acknowledge clock pulse (see *Figure 29*). The receiver^(**) the acknowledges has to pull-down (LOW) the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during this clock pulse.

(*) Transmitter

- master (μP) when it writes an address to the TDA7563PD
- slave (TDA7563PD) when the μP reads a data byte from TDA7563PD

(**) Receiver

- slave (TDA7563PD) when the μP writes an address to the TDA7563PD
- master (μP) when it reads a data byte from TDA7563PD

Figure 27. Data validity on the I²C bus

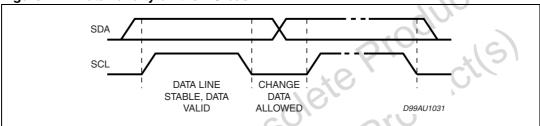


Figure 28. Timing diagram on the I²C bus

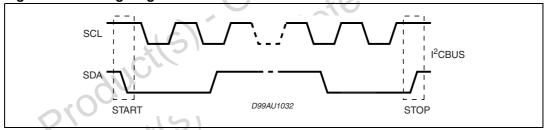
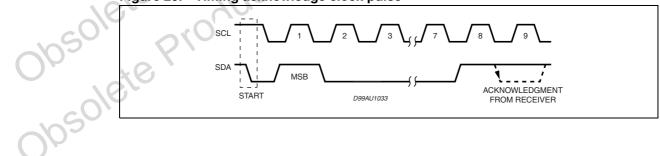


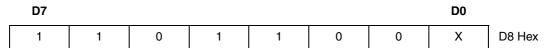
Figure 29. Timing acknowledge clock pulse



Software specifications 7

All the functions of the TDA7563PD are activated by I^2C interface.

The bit 0 of the "ADDRESS BYTE" defines if the next bytes are write instruction (from μP to TDA7563PD) or read instruction (from TDA7563PD to μP).



X = 0 Write to device

Table 5. IB1

Table 5.	IB1 Instruction
D7	x
D6	Diagnostic enable (D6 = 1) Diagnostic defeat (D6 = 0)
D5	Offset Detection enable (D5 = 1) Offset Detection defeat (D5 = 0)
D4	Front Channel Gain = 30dB (D4 = 0) Gain = 16dB (D4 = 1)
D3	Rear Channel Gain = 30dB (D3 = 0) Gain = 16dB (D3 = 1)
D2	Mute front channels (D2 = 0) Unmute front channels (D2 = 1)
D1	Mute rear channels (D1 = 0) Unmute rear channels (D1 = 1)
DO	CD 2% (D0 = 0) CD 10% (D0 = 1)

Table 6. IB2

Bit	Instruction
D7	X
D6	Used for testing
D5	Used for testing
D4	Standby on - Amplifier not working - (D4 = 0) Standby off - Amplifier working - (D4 = 1)
D3	Power amplifier mode diagnostic (D3 = 0) Line driver mode diagnostic (D3 = 1)
D2	X
D1	Right Channel Power amplifier working in standard mode (D1 = 0) Power amplifier working in high efficiency mode (D1 = 1)
D0	Left Channel Power amplifier working in standard mode (D0 = 0) Power amplifier working in high efficiency mode (D0 = 1)

If R/W = 1, the TDA7563PD sends 4 "Diagnostics Bytes" to μ P: DB1, DB2, DB3 and DB4.

Table 7. DB1

	Bit	Instruction
	D7	Thermal warning active (D7 = 1)
	D6	Diag. cycle not activated or not terminated (D6 = 0) Diag. cycle terminated (D6 = 1)
	D5	x (3)
	D4	Channel LF Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
16	D3	Channel LF Normal load (D3 = 0) Short load (D3 = 1)
Obsole	D2	Channel LF Turn-on diag.: No open load (D2 = 0)
Obso	D1	Channel LF No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
	D0	Channel LF No short to GND (D1 = 0) Short to GND (D1 = 1)

Table 8. DB2

Bit	Instruction
D7	Offset detection not activated (D7 = 0)
D/	Offset detection activated (D7 = 1)
D6	X
D5	X
	Channel LR
D4	Turn-on diagnostic (D4 = 0)
	Permanent diagnostic (D4 = 1)
	Channel LR
D3	Normal load (D3 = 0)
	Short load (D3 = 1)
	Channel LR
	Turn-on diag.: No open load (D2 = 0)
D2	Open load detection (D2 = 1)
	Permanent diag.: No output offset (D2 = 0)
	Output offset detection (D2 = 1)
	Channel LR
D1	No short to Vcc (D1 = 0)
	Short to Vcc (D1 = 1)
	Channel LR
D0	No short to GND (D1 = 0)
	Short to GND (D1 = 1)

Table 9. DB3

	Bit	Instruction
	D7	Standby status (= IB2 - D4)
	D6	Diagnostic status (= IB1 - D6)
	D5	x (S)
	2.	Channel RF
	D4	Turn-on diagnostic (D4 = 0)
		Permanent diagnostic (D4 = 1)
1250	0	Channel RF
	D3	Normal load (D3 = 0)
0'	3	Short load (D3 = 1)
78,		Channel RF
cO'		Turn-on diag.: No open load (D2 = 0)
203	D2	Open load detection (D2 = 1)
() 9		Permanent diag.: No output offset (D2 = 0)
		Output offset detection (D2 = 1)
		Channel RF
	D1	No short to Vcc (D1 = 0)
		Short to Vcc (D1 = 1)
		Channel RF
	D0	No short to GND (D1 = 0)
		Short to GND (D1 = 1)

Table 10. DB4

	Bit	Instruction						
	D7	X						
	D6	X						
	D5	X						
	D4	Channel RR Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)						
	D3	Channel R R Normal load (D3 = 0) Short load (D3 = 1)						
	D2	Channel RR Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)						
	D1	Channel RR No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)						
	D0	Channel RR No short to GND (D1 = 0) Short to GND (D1 = 1)						
Obsole Obsole	teP	roduci(s) obsoleto						

Examples of bytes sequence 8

1 - Turn-On diagnostic - Write operation

Start Address byte with D0 = 0	ACK	IB1 with D6 = 1	ACK	IB2	ACK	STOP
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2 - Turn-On diagnostic - Read operation

	<u> </u>										
Start	Address byte with D0 = 1	ACK	DB1	ACK	DB2	ACK	DB3	ACK	DB4	ACK	STOP

The delay from 1 to 2 can be selected by software, starting from 1ms

3a - Turn-On of the power amplifier with 30dB gain, mute on, diagnostic defeat, CD = 2%.

Start	Address byte with D0 = 0	ACK IB1		ACK	ACK IB2		TOP
			X0000000		XXX1XX11	4/5	1

3b - Turn-Off of the power amplifier

Start	Address byte with D0 = 0		IB1	ACK IB2		ACK	STOP
		X0XXXX			XXX0XXXX		51

4 - Offset detection procedure enable

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			XX1XX11X		XXX1XXXX		

5 - Offset detection procedure stop and reading operation (the results are valid only for the offset detection bits (D2 of the bytes DB1, DB2, DB3, DB4).

 	· · · · · · · · · · · · · · · · · · ·	,	,	· , ,							
Start	Address byte with D0 = 1	ACK	DB1	ACK	DB2	ACK	DB3	ACK	DB4	ACK	STOP

- anomalous 4 to 5 can be se The purpose of this test is to check if a D.C. offset (2V typ.) is present on the outputs, produced by input capacitor with anomalous leakage current or humidity between pins.
 - The delay from 4 to 5 can be selected by software, starting from 1ms.

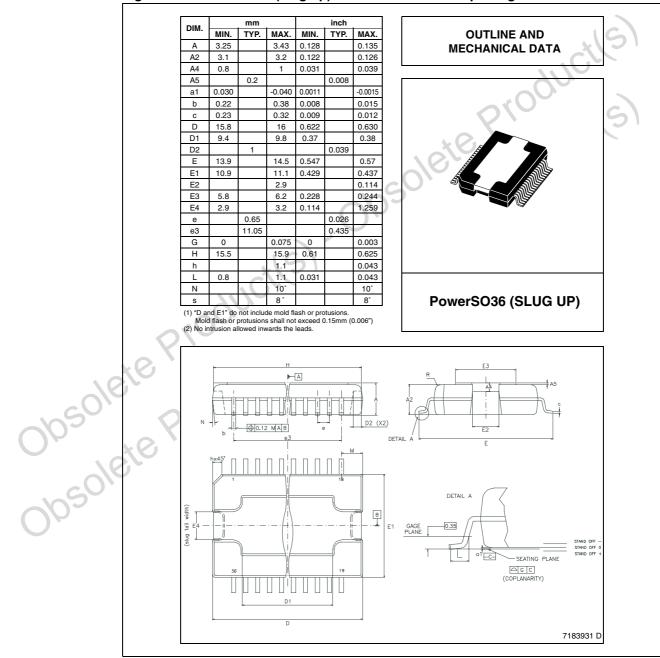
TDA7563PD Package information

9 Package information

In order to meet environmental requirements, ST (also) offers these devices in ECOPACK[®] packages. ECOPACK[®] packages are lead-free. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label.

ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Figure 30. PowerSO36 (slug up) mechanical data and package dimensions



Revision history TDA7563PD

10 Revision history

Table 11. Document revision history

Date	Revision	Changes
20-Apr-2008	1	Initial release.
03-Dec-2008	2	Document reformatted. Document status promoted from product preview to datasheet. Updated Section 9: Package information.

Obsolete Producits). Obsolete Producits) obsolete Producits) obsolete Producits).

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